

DIODE MODULE 250A/300 to 800V PH2503,PH2504,PH2508

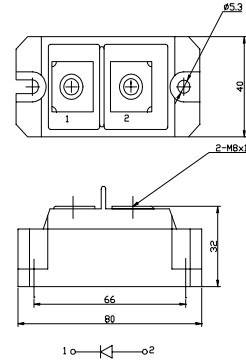
FEATURES

- * Isolated Base
- * High Surge Capability
- * UL Recognized, File No. E187184

TYPICAL APPLICATIONS

- * Rectified For General Use

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:220g

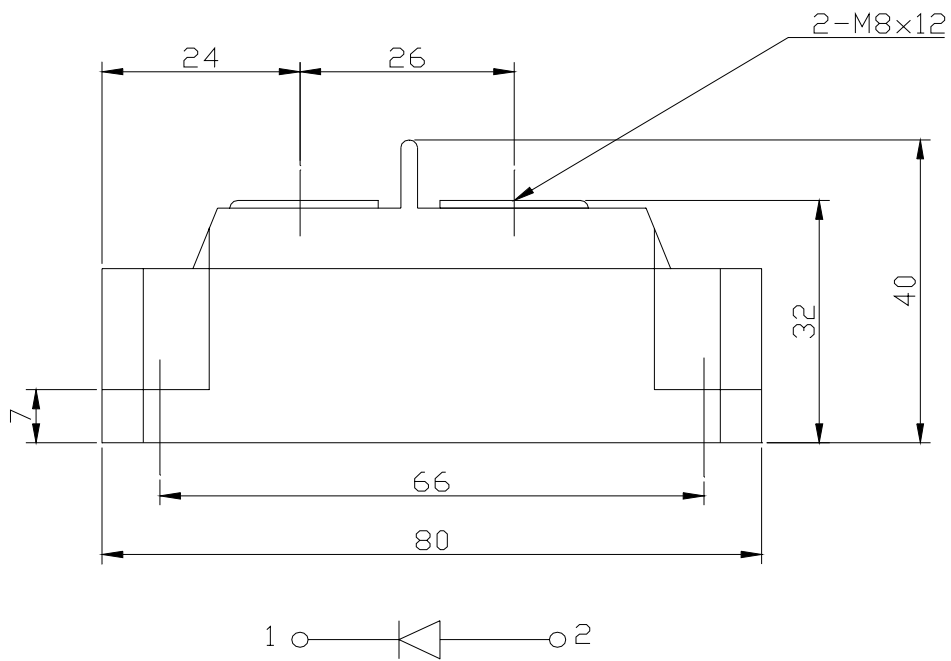
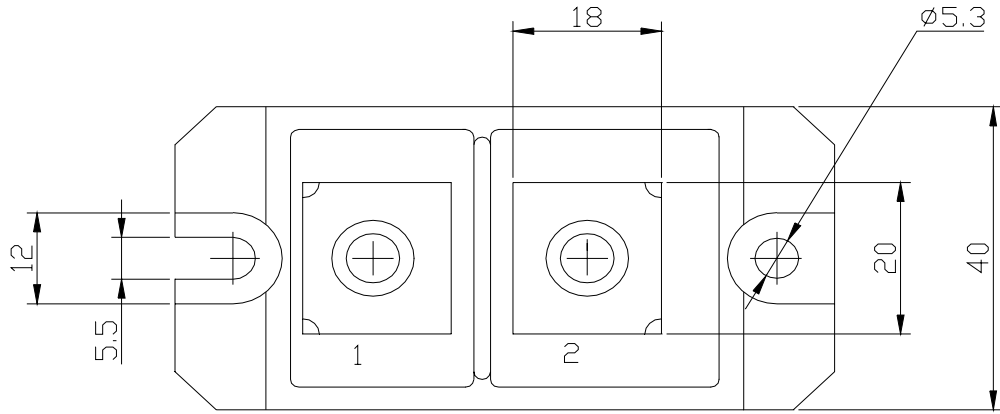
Parameter	Symbol	Type / Grade			Unit
		PH2503	PH2504	PH2508	
Repetitive Peak Reverse Voltage	V_{RRM}	300	400	800	V
Non Repetitive Peak Reverse Voltage	V_{RSM}	400	500	900	

Parameter		Conditions	Max Rated Value	Unit	
Average Rectified Output Current	$I_{O(AV)}$	50Hz Half Sine Wave condition $T_c=95^\circ\text{C}$	250	A	
RMS Forward Current	$I_{F(RMS)}$		390	A	
Surge Forward Current	I_{FSM}	50 Hz Half Sine Wave,1Pulse Non-repetitive	5000	A	
I Squared t	I^2t	2msec to 10msec	125000	A^2s	
Operating JunctionTemperature Range	T_{jw}		-40 to +150	$^\circ\text{C}$	
Storage Temperature Range	T_{stg}		-40 to +125	$^\circ\text{C}$	
Isolation Voltage	Viso	Base Plate to Terminals, AC1min	2000	V	
Mounting torque	Case mounting	Ftor	M5 Screw	2.4 to 2.8	N.m
	Terminals		M8 Screw	9.0 to 10.0	

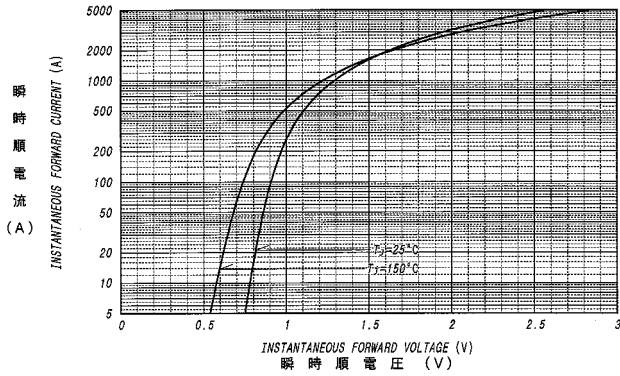
Electrical • Thermal Characteristics

Characteristics	Symbol	Test Conditions	Max.	Unit
Peak Reverse Current	I_{RM}	$V_{RM}= V_{RRM}, T_j= 150^\circ\text{C}$	40	mA
Peak Forward Voltage	V_{FM}	$I_{FM}= 800\text{A}, T_j=25^\circ\text{C}$	1.22	V
Thermal Resistance	$R_{th(j-c)}$	Junction to Case	0.2	$^\circ\text{C}/\text{W}$
	$R_{th(c-f)}$	Base Plate to Heat Sink with Thermal Compound	0.1	

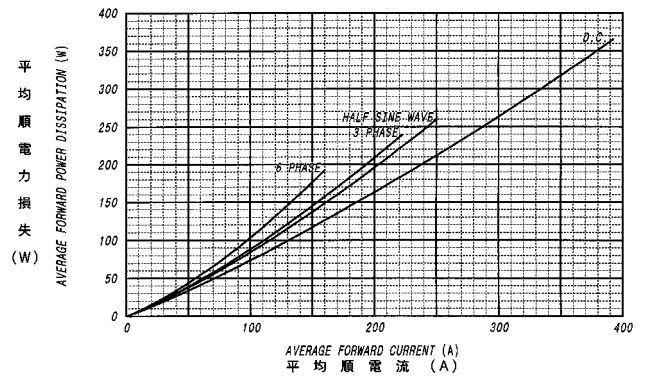
PH250x OUTLINE DRAWING (Dimensions in mm)



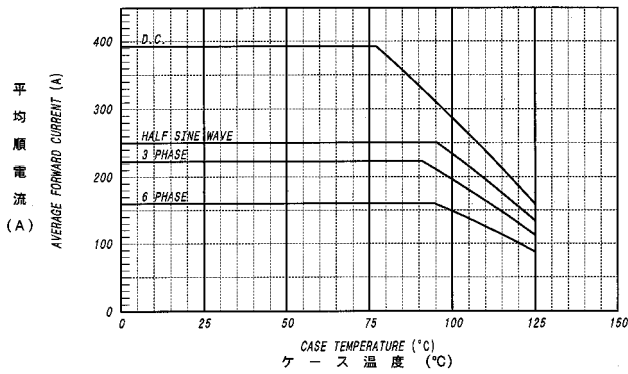
順電圧特性
FORWARD CURRENT VS. VOLTAGE



平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION

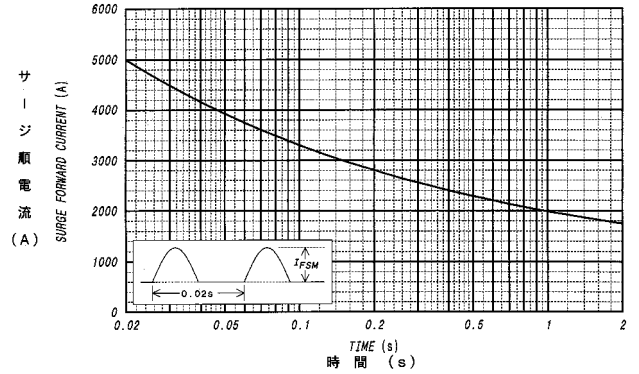


平均順電流 - ケース温度定格
AVERAGE FORWARD CURRENT VS. CASE TEMPERATURE



サージ順電流定格
SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, Tj=150°C



過渡熱抵抗特性
MAXIMUM TRANSIENT THERMAL IMPEDANCE
Junction to Case

